



## **SL-T1516RGBA-L150-N**

Approved By: Checked By: Prepared By:

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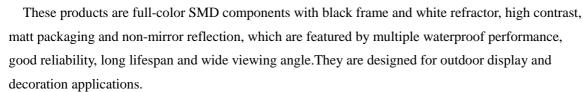




### **SL-T1516RGBA-L150-N**

#### **Full-color LED** TOP

#### **Technical Data Sheet**





Features:

Material:

Red Green Blue AlGaInP InGaN InGaN

**Encapsulation:** Epoxy Resin

Soldering methods: Pb-Free reflow soldering

High Luminous Intensity ,Low Power Dissipation, good Reliability and Long Life

Complied With ROHS Directive

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<sup>\*</sup> The specifications of the product may be modified for improvement without notice.





### **Electro-Optical Characteristics**

♦ Absolute Maximum Ratings (Temperature=25 °C)

Parameter		Symbol	Rating	Unit
Forward Current		${ m I_F}$	25	mA
* Pulse Forward Current*		$I_{\mathrm{FP}}$	50	mA
Reverse Voltage		$V_R$	5	V
Operating Temperature		Tamd	-30 ~ +85	
Storage Temperature		Tstg	-40 ~ +100	
	Red		62.5	
Power Dissipation	Green	Ptot	85	mW
1 ower Dissipation	Blue		85	

0.1ms

1/10

\* Note: Pulse Width 0.1ms, Duty 1/10

Electro-Optical Characteristics (Temperature=25  $^{\circ}$ C)

Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Reverse Current	$I_R$	VR=5 V	Red			10	
			Green			10	
			Blue			10	
Forward Voltage	$V_F$	IF=15mA	Red	1.8	2.1	2.5	V
		IF=8mA	Green	2.4	2.9	3.4	
		IF=5mA	Blue	2.4	2.9	3.4	
	D	IF=15mA	Red	615	622	630	nm
Dominant Wavelength		IF=8mA	Green	515	528	540	
Dominant wavelength		IF=5mA	Blue	460	469	480	
		IF=15mA	Red			24	
Spectrum Radiation		IF=8mA	Green			38	nm
Bandwidth		IF=5mA	Blue			28	
Luminous Intensity	$I_{V}$	IF=15mA	Red	200	370	560	mcd
		IF=8mA	Green	320	560	850	
		IF=5mA	Blue	40	80	130	
View Angle	2 1/2				110		deg.

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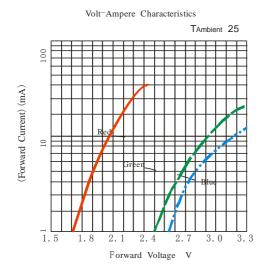
manufacturer

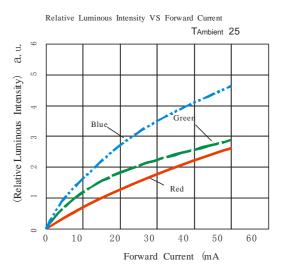
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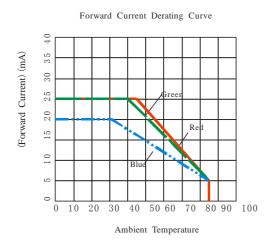


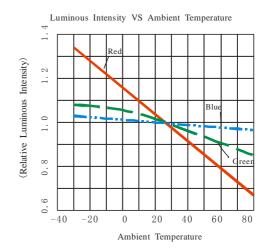


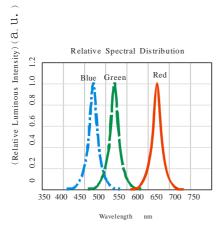
#### **Typical Characteristics Curves**

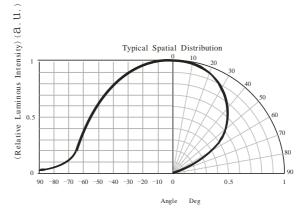










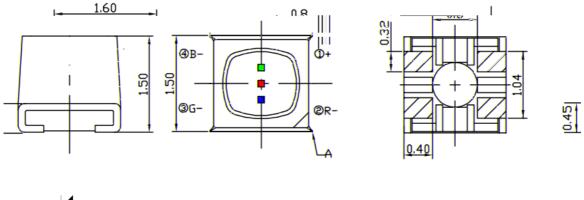




#### **Product Design and Operating Recommendation**

1 mm

Product design Unit: mm



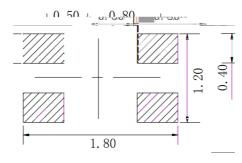


Polarity

Note A A Nick Mark

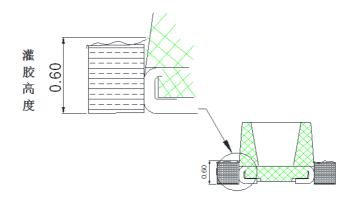
2 mm

Reference soldering pad (Unit: mm)



3 0.60mm

Recommendation for glue filling: filling height must be higher than or equal to 0.60mm

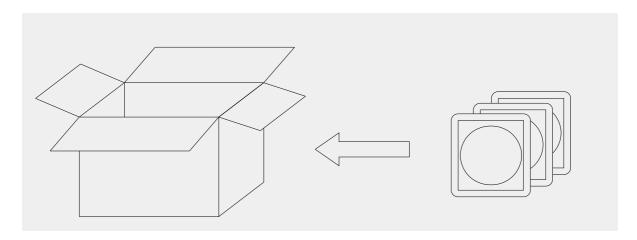






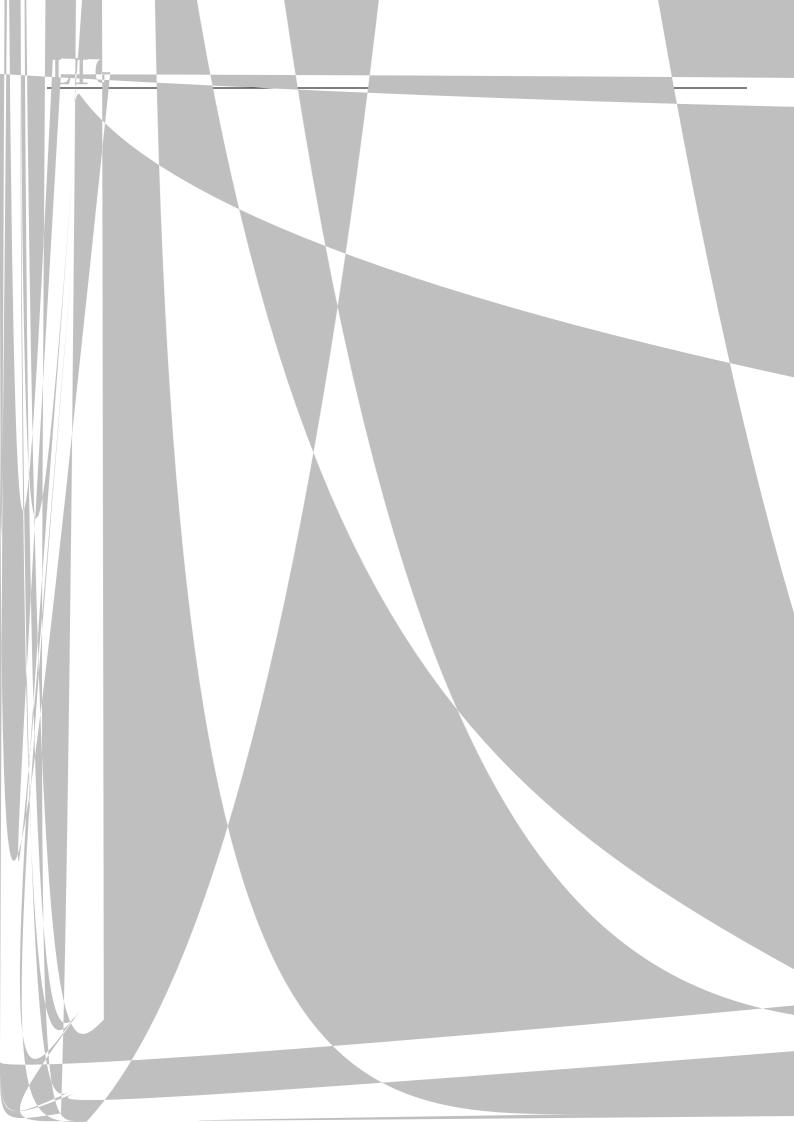


 $\diamondsuit$ · Cardboard Box



· Label Explanation









**(1)** 

#### **Precautions (1)**

1.

#### Storage

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Moisture proof, anti-electrostatic package and moisture absorbent material are used, to keep moisture to a minimum. Humidity indicator card inside to test if the products are moisted.

• <30 <60 RH

Storage environment: All the products should be stored in the environment of temperature<30 and humidity<60 RH before foiled bags open and need to be baked before SMT.

Before using, please check whether there is any air leakage or not, If the bag has leaked air, Please bake the product with below condition.

• <30 <60 RH 8h

Before soldering ,the product must be stored under the condition of <30 and <60 RH. Under these conditions the SMD LEDs must be used (subject to reflow oven) within 8 hours.

• 70±5 12h 70±5 24h

6 70±5 48h

Baking condition storage undamped :  $70\pm5$  ×12h

e (undamped):  $70\pm5$  ×24h

Damped/Foiled bag leakage/ beyond 6 months storage at customers side: 70±5 ×48h

2.

#### **Static Electricity**

•

# **LIGHT**





**(3)** 

#### **Precautions (3)**

Such as the reverse current increase rapidly. And it will cause the string light when the screen is black. So please pay attention to controlling the reverse voltage which less than 5V is recommended.

5.

#### The safe temperature for LEDs working

LED

55 75

The high temperature will make

are used in hot

environment for a long time, they will be disabled easily. When LEDs are used in a high density array, we suggest that the LEDs

and the

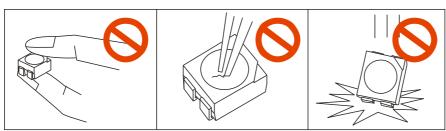
lower than 75 .

6.

Others

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When handling the product, touching the encapsulation with bare hands will not only contaminate its surface, but also have an effect on its optical characteristics. Excessive force to the encapsulation might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



• LED

The epoxy resin of encapsulation is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.